

TRADE ACCES DOCUMENTS

From: [REDACTED]
Sent: samedi 14 mai 2022 22:38
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WHELAN Anthony (CAB-VON DER LEYEN); [REDACTED]; CAB DOMBROVSKIS CONTACT; CAB VESTAGER CONTACT
Subject: Open letter to the EU-US Trade and Technology Council from ERICSSON, HP, IBM, MICROSOFT, NOKIA, SALESFORCE, SAP & SCHNEIDER ELECTRIC
Attachments: TTC Open Letter final 13 May.pdf

Dear Michael & Kim,

Please find attached Open Letter to the EU-U.S. Trade & Technology Council (TTC) ahead of tomorrow's Second Ministerial Meetings in Paris Saclay, France by a group of American and European headquartered companies which are strongly committed to the transatlantic partnership setting out some recommendation for TTC deliverables. We are forwarding this for the attention of Executive Vice President Dombrovskis, Executive Vice President Vestager, Secretary of State Blinken, Secretary of Commerce Raimondo & U.S. Trade Representative Tai.

We would be delighted to discuss the work of the TTC and our recommendations with you in the coming weeks, at a time and in a format most convenient to you.

For your information we are in Washington DC sending a copy of the letter to:

- Mr Jayme White, Deputy United States Trade Representative
- Marisa Lago Undersecretary of Commerce for International Trade
- Mr Alan Estevez, Undersecretary of Commerce for Industry and Security
- Mr Jose Fernandez, Undersecretary of State for Economic Growth, Energy, and the Environment

With our best regards and on behalf of

ERICSSON, HP, IBM, MICROSOFT, NOKIA, SALESFORCE, SAP & SCHNEIDER ELECTRIC

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